Variant: 001

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TIDA-01527 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01527	Any	Printed Circuit Board	
2	C2, C3	2	1uF	GCM31CR72A105KA03	MuRata	CAP, CERM, 1 µF, 100 V,+/- 10%, X7R, AEC-Q200 Grade 1, 1206	1206
3	D1	1	60V	SS16T3G	ON Semiconductor	Diode, Schottky, 60 V, 1 A, SMA	SMA
4	J1	1		SSQ-107-03-G-D	Samtec	Receptacle, 100mil, 7x2, Gold, TH	SSQ-107-03-G-D
5	J2	1		1725656	Phoenix Contact	Terminal Block, 100mil, 2x1, 6A, 63V, TH	6.2x8.5x5.54 mm
6	J13, J42	2		SSW-110-21-S-D	Samtec	Receptacle, 2.54mm, 10x2, Gold, TH	Receptacle, 2.54mm,
							10x2, TH
7	TP1, TP2, TP3,	6		5005	Keystone	Test Point, Compact, Red, TH	Red Compact
	TP4, TP5, TP6						Testpoint

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